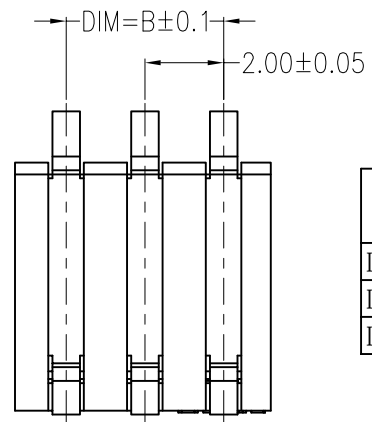
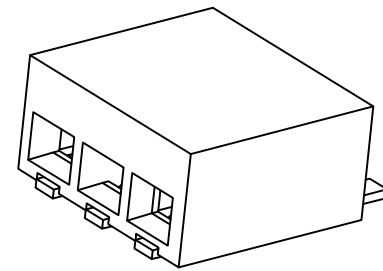
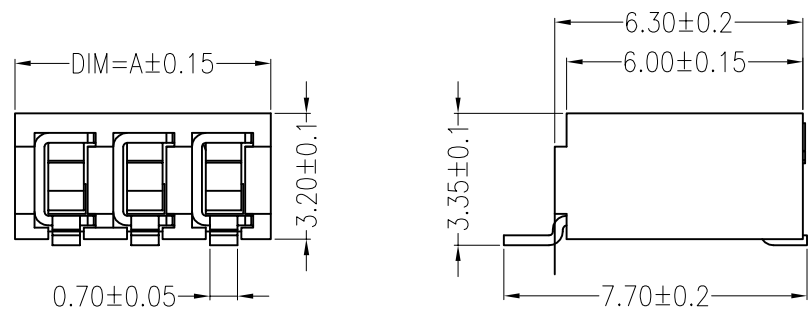
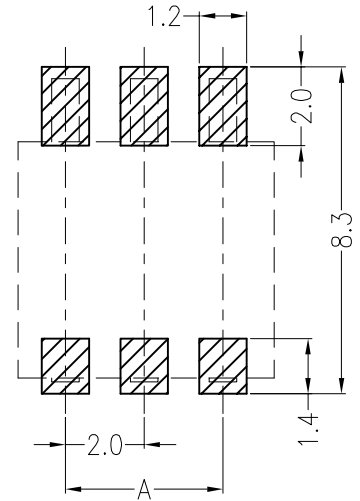


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



Circuit	Dimensions (mm)	
	DIM=A	DIM=B
L023Y-01	2.50	
L023Y-02	4.50	2.00
L023Y-03	6.50	4.00



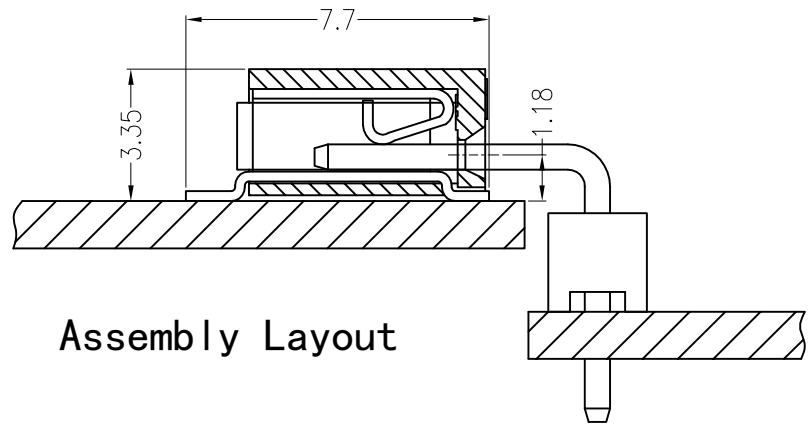
主要技术参数 Main Specifications

- 线 数 (Poles): 01 to 03
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 1000M\Omega$
- 额定电压 (Rated voltage): 125V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐 电压 (Withstand Voltage): 1000V AC/minute
- 温度范围 (Temperature Range): $-25^{\circ}C \sim +105^{\circ}C$

ORDER INFORMATION:

L023Y--F2MB-P**

PART No.:		PACKAGING:	
No. FOR CIRCUITS:		P=PE	
01~03		R=REEL	
PLASTIC MATERIAL:		PLATING:	
F2M=LCP (BEIGE)		B=MATTE Sn	



Assembly Layout

Board Layout

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C				
B	CONTACT	1~3 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

广东科斯达电子科技有限公司 GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.		TITLE: -	
		2.0mmPITCH 90°WAFER SMT TYPE	
X.±0.5	X.±5°	USE:	PART NO.:
.X±0.3	.X±2°	CUSTOMER	L023Y-**-F2MB-R
.XX±0.25	.XX±1°	APPD:	DWG NO.:
--	--	邵敬和	GCCP-0044
⊕	∠	CHKD:	SCALE
UNITS: mm	周秀龙	田峰	1 : 1
		DR:	SHEET
			1 / 1